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July 2015

FAN5400/FAN5401/FAN5402/FAN5403/FAN5404/FAN5405 USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Faster Charging than Linear
- Charge Voltage Accuracy: ±0.5% at 25°C ±1% from 0 to 125°C
- ±5% Input Current Regulation Accuracy
- ±5% Charge Current Regulation Accuracy
- 20 V Absolute Maximum Input Voltage
- 6 V Maximum Input Operating Voltage
- 1.25 A Maximum Charge Rate
- Programmable through High-Speed I²C Interface (3.4 Mb/s) with Fast Mode Plus Compatibility
 - Input Current
 - Fast-Charge / Termination Current
 - Charger Voltage
 - Termination Enable
- 3 MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1 µH External Inductor
- Safety Timer with Reset Control
- 1.8 V Regulated Output from VBUS for Auxiliary Circuits
- Weak Input Sources Accommodated by Reducing Charging Current to Maintain Minimum VBUS Voltage
- Low Reverse Leakage to Prevent Battery Drain to VBUS
- 5 V, 300 mA Boost Mode for USB OTG for 2.5 to 4.5 V Battery Input

Applications

- Cell Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras

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Description

The FAN5400 family (FAN540x) combines a highly integrated switch-mode charger, to minimize single-cell Lithium-ion (Li-ion) charging time from a USB power source, and a boost regulator to power a USB peripheral from the battery.

The charging parameters and operating modes are programmable through an I^2C Interface that operates up to 3.4 Mbps. The charger and boost regulator circuits switch at 3 MHz to minimize the size of external passive components.

The FAN540X provides battery charging in three phases: conditioning, constant current, and constant voltage.

To ensure USB compliance and minimize charging time, the input current is limited to the value set through the I^2C host. Charge termination is determined by a programmable minimum current level. A safety timer with reset control provides a safety backup for the I^2C host.

The integrated circuit (IC) automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode with leakage from the battery to the input prevented. Charge status is reported back to the host through the l^2C port. Charge current is reduced when the die temperature reaches 120°C.

The FAN540X can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery.

The FAN540X is available in a 1.96 x 1.87 mm, 20-bump, 0.4 mm pitch, WLCSP package.

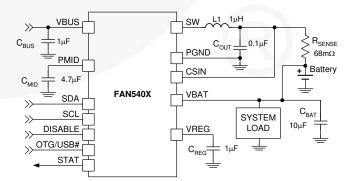


Figure 1. Typical Application (FAN5403-05 Pin Out)

Ordering Information

Part Number	Temperature Range	Package	PN Bits: IC_INFO[4:3]	Packing Method
FAN5400UCX	-40 to 85°C		01	Tape and Reel
FAN5401UCX	-40 to 85°C		00	Tape and Reel
FAN5402UCX	-40 to 85°C	20-Bump, Wafer- Level Chip-Scale	01	Tape and Reel
FAN5403UCX	-40 to 85°C	Package (WLCSP),	10	Tape and Reel
FAN5403BUCX ⁽¹⁾	-40 to 85°C	0.4 mm Pitch,	10	Tape and Reel
FAN5404UCX	-40 to 85°C	Estimated Size: 1.96 x 1.87 mm	11	Tape and Reel
FAN5405UCX	-40 to 85°C		10	Tape and Reel
FAN5405BUCX ⁽¹⁾	-40 to 85°C		10	Tape and Reel

Note:

1. FAN5403BUCX and FAN5405BUCX Includes backside lamination

Table 1. Feature Comparison Summary

Part Number	PN Bits: REG3[4:3]	Slave Address	Automatic Charge	Special Charger ⁽²⁾	Safety Limits	Battery Absent Behavior	E2 Pin	VREG (E3 Pin)
FAN5400	01	1101011	Yes	No	No	OFF	AUXPWR	
FAN5401	00	1101011	No	No	No	OFF	(Connect to VBAT)	PMID
FAN5402	01	1101011	Yes	No	No	ON		
FAN5403	10	1101011	Yes	Yes	Yes	OFF		
FAN5404	11	1101011	No	Yes	Yes	OFF	DISABLE	1.8V
FAN5405	10	1101010	Yes	Yes	Yes	ON		

Note:

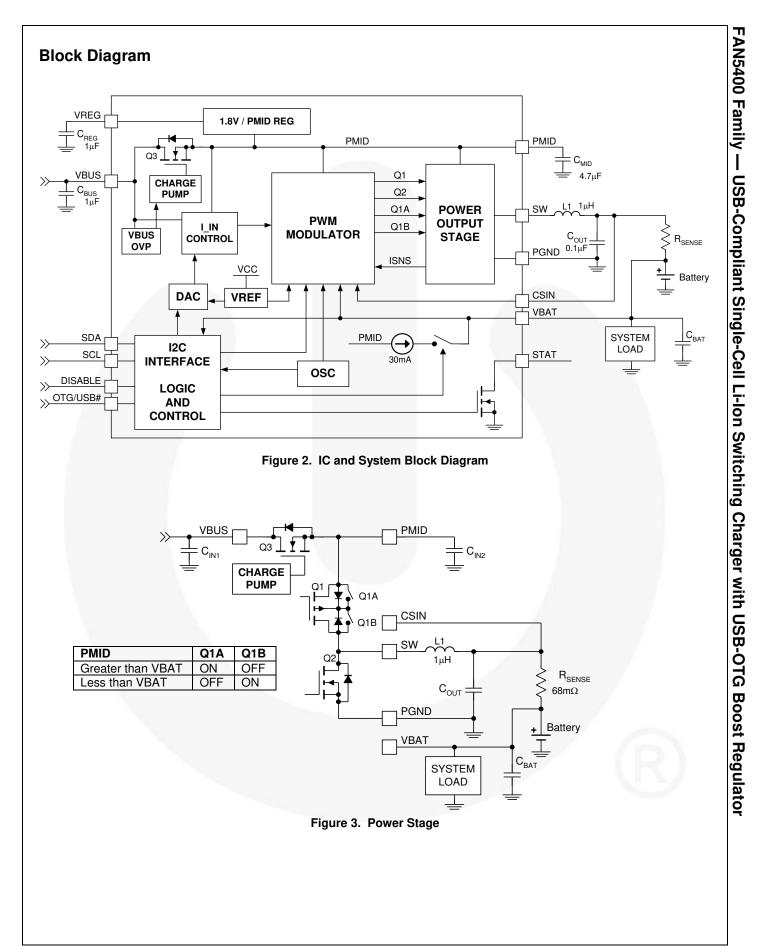
2. Special charger is a current limited charger that is not a USB compliant source.

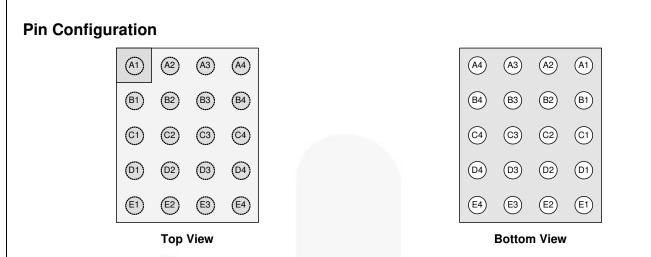
Table 2. Recommended External Components

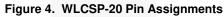
Component	Description	Vendor	Parameter	Тур.	Unit
L1	1 11 000/ 1 0 0 0010	Murata: LQM2MPN1R0M	L	1.0	μH
LI	1 μH, 20%, 1.3 A, 2016	or Equivalent DCR (S		85	mΩ
Сват	10 μF, 20%, 6.3 V, X5R, 0603	Murata: GRM188R60J106M TDK: C1608X5R0J106M	С	10	μF
C _{MID}	4.7 μF, 10%, 6.3 V, X5R, 0603	Murata: GRM188R60J475K TDK: C1608X5R0J475K	C ⁽³⁾	4.7	μF
C _{BUS}	1.0 μF, 10%, 25 V, X5R, 0603	Murata GRM188R61E105K TDK:C1608X5R1E105M	С	1.0	μF

Note:

3. 6.3 V rating is sufficient for C_{MID} since PMID is protected from over-voltage surges on VBUS by Q3 (Figure 3).







Pin Definitions

Pin #	Name	Part #	Description
A1, A2	VBUS	ALL	Charger Input Voltage and USB-OTG output voltage. Bypass with a 1 μ F capacitor to PGND.
A3	NC	ALL	No Connect . No external connection is made between this pin and the IC's internal circuitry.
A4	SCL	ALL	I ² C Interface Serial Clock. This pin should not be left floating.
B1-B3	PMID	ALL	Power Input Voltage . Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 4.7 μ F, 6.3 V capacitor to PGND.
B4	SDA	ALL	I ² C Interface Serial Data. This pin should not be left floating.
C1-C3	SW	ALL	Switching Node. Connect to output inductor.
C4	STAT	ALL	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charge is in process.
D1-D3	PGND	ALL	Power Ground . Power return for gate drive and power transistors. The connection from this pin to the bottom of C_{MID} should be as short as possible.
D4	OTG	ALL	On-The-Go . Enables boost regulator in conjunction with OTG_EN and OTG_PL bits <i>(see Table 16)</i> . On VBUS Power-On Reset (POR), this pin sets the input current limit for t _{15MIN} charging.
E1	CSIN	ALL	Current-Sense Input . Connect to the sense resistor in series with the battery. The IC uses this node to sense current into the battery. Bypass this pin with a 0.1 μ F capacitor to PGND.
E2	AUXPWR	FAN5400, FAN5401, FAN5402	Auxiliary Power. Connect to the battery pack to provide IC power during High-Impedance Mode. Bypass with a 1 μ F capacitor to PGND.
E2	DISABLE	FAN5403, FAN5404, FAN5405	Charge Disable . If this pin is HIGH, charging is disabled. When LOW, charging is controlled by the I ² C registers. When this pin is HIGH, the 15-minute timer is reset. This pin does not affect the 32-second timer.
E3	VREG	ALL	Regulator Output . Connect to a 1 μ F capacitor to PGND. This pin can supply up to 2 mA of DC load current. For FAN5400-FAN5402, the output voltage is PMID, which is limited to 6.5 V. For FAN5403-FAN5405, the output voltage is regulated to 1.8 V.
E4	VBAT	ALL	Battery Voltage . Connect to the positive $(+)$ terminal of the battery pack. Bypass with a 0.1 μ F capacitor to PGND if the battery is connected through long leads.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

	Para	ameter	Min.	Max.	Unit
	Co	ntinuous	-1.4	20.0 16.0 7.0 7.0 6.5 ⁽⁴⁾ 4 2000	V
VBUS Vollage	Pu	lsed, 100 ms Maximum Non-Repetitive	-2.0		v
STAT Voltage			-0.3	16.0	V
PMID Voltage				7.0	v
SW, CSIN, VBAT, AUXPV	WR, DISABL	E Voltage	-0.3	7.0	v
Voltage on Other Pins			-0.3	6.5 ⁽⁴⁾	V
Maximum VBUS Slope ab	oove 5.5 V w	hen Boost or Charger are Active		4	V/µs
Electrostatic Discharge	Hu	man Body Model per JESD22-A114	20	000	v
Protection Level	Ch	arged Device Model per JESD22-C101	5	00	v
Junction Temperature			-40	+150	°C
Storage Temperature			-65	+150	°C
Lead Soldering Temperate	ure, 10 Seco	onds		+260	°C
	PMID Voltage SW, CSIN, VBAT, AUXPV Voltage on Other Pins Maximum VBUS Slope at Electrostatic Discharge Protection Level Junction Temperature Storage Temperature	VBUS Voltage Co VBUS Voltage Pu STAT Voltage STAT Voltage SW, CSIN, VBAT, AUXPWR, DISABL Voltage on Other Pins Maximum VBUS Slope above 5.5 V w Electrostatic Discharge Protection Level Hu Junction Temperature Storage Temperature	Pulsed, 100 ms Maximum Non-Repetitive STAT Voltage PMID Voltage SW, CSIN, VBAT, AUXPWR, DISABLE Voltage Voltage on Other Pins Maximum VBUS Slope above 5.5 V when Boost or Charger are Active Electrostatic Discharge Protection Level Human Body Model per JESD22-A114 Charged Device Model per JESD22-C101 Junction Temperature	VBUS VoltageContinuous-1.4Pulsed, 100 ms Maximum Non-Repetitive-2.0STAT Voltage-0.3PMID Voltage-0.3SW, CSIN, VBAT, AUXPWR, DISABLE Voltage-0.3Voltage on Other Pins-0.3Voltage on Other Pins-0.3Maximum VBUS Slope above 5.5 V when Boost or Charger are Active-0.3Electrostatic Discharge Protection LevelHuman Body Model per JESD22-A11420Junction Temperature-40Storage Temperature-65	VBUS VoltageContinuous-1.420.0Pulsed, 100 ms Maximum Non-Repetitive-2.020.0STAT Voltage-0.316.0PMID Voltage-0.37.0SW, CSIN, VBAT, AUXPWR, DISABLE Voltage-0.37.0Voltage on Other Pins-0.36.5 ⁽⁴⁾ Maximum VBUS Slope above 5.5 V when Boost or Charger are Active4Electrostatic Discharge Protection LevelHuman Body Model per JESD22-A1142000Junction Temperature-40+150Storage Temperature-65+150

Note:

4. Lesser of 6.5 V or V_1 + 0.3 V.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter		Min.	Max.	Units
V _{BUS}	Supply Voltage		4	6	V
V _{BAT(MAX)}	Maximum Battery Voltage when Boost enabled			4.5	V
dV _{BUS}	Negative VBUS Slew Rate during VBUS Short Circuit,	T _A <u><</u> 60°C		4	
dt	$C_{\text{MID}} \leq 4.7 \ \mu\text{F}$, see VBUS Short While Charging	T _A <u>≥</u> 60°C		2	V/μs
T _A	Ambient Temperature		-30	+85	°C
TJ	Junction Temperature (see Thermal Regulation and Prote	ection section)	-30	+120	°C

Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature $T_{J(max)}$ at a given ambient temperature T_A . *For measured data, see Table 11.*

Symbol	Parameter	Typical	Units
θ」Α	Junction-to-Ambient Thermal Resistance	60	°C/W
θ_{JB}	Junction-to-PCB Thermal Resistance	20	°C/W

Electrical Specifications

Unless otherwise specified: according to the circuit of Figure 1; recommended operating temperature range for T_J and T_A ; V_{BUS} =5.0 V; HZ_MODE; OPA_MODE=0; (Charge Mode); SCL, SDA, OTG=0 or 1.8 V; and typical values are for T_J =25°C.

Symbol	Parameter	Condi	Min.	Тур.	Max.	Units		
Power Supp	lies			1			<u> </u>	
		$V_{BUS} > V_{BUS(min)}, PW$	M Switching		10		mA	
I _{VBUS}	VBUS Current	V _{BUS} > V _{BUS(min)} ; PW Not Switching (Batte Condition); I_IN Set	ery OVP		2.5		mA	
		0°C < T _J < 85°C, H2 V _{BAT} < V _{LOWV} , 32S M			63	90	μA	
I _{LKG}	VBAT to VBUS Leakage Current	$0^{\circ}C < T_J < 85^{\circ}C, HZ$ V _{BAT} =4.2 V, V _{BUS} =0	Z_MODE=1, V		0.2	5.0	μA	
I	Battery Discharge Current in High-	0°C < T _J < 85°C, H2 V _{BAT} =4.2 V	Z_MODE=1,			20		
I _{BAT}	Impedance Mode	FAN5403-05, DISA 0°C < T _J < 85°C, V _B				10	μΑ	
Charger Vol	tage Regulation							
	Charge Voltage Range			3.5		4.4		
VOREG	Charge Voltage Accuracy	T _A =25°C		-0.5%		+0.5%	V	
	Charge voltage Accuracy	T _J =0 to 125°C		-1%		+1%		
Charging Cu	urrent Regulation							
	Output Charge Current Range	$V_{LOWV} < V_{BAT} < V_{ORE}$ $V_{BUS} > V_{SLP}, R_{SENSE}$		550		1250	mA	
	Charge Current Accuracy Across	20 mV <u><</u> V _{IREG} <u><</u>	FAN5400-02	95	100	105		
IOCHRG		40 mV	FAN5403-05	92	97	102	%	
		V _{IREG} > 40 mV	FAN5400-02	97	100	103	/0	
		$V_{\rm IREG} > 40 \mathrm{mv}$	FAN5403-05	94	97	100		
Weak Batter	y Detection							
	Weak Battery Threshold Range			3.4		3.7	V	
V_{LOWV}	Weak Battery Threshold Accuracy			-5		+5	%	
	Weak Battery Deglitch Time	Rising Voltage, 2 m	V Overdrive		30		ms	
Logic Levels	s: DISABLE, SDA, SCL, OTG							
VIH	High-Level Input Voltage			1.05			V	
VIL	Low-Level Input Voltage				1	0.4	V	
I _{IN}	Input Bias Current	Input Tied to GND c	r V _{IN}		0.01	1.00	μA	
Charge Tern	nination Detection	-						
	Termination Current Range	$V_{\text{BAT}} > V_{\text{OREG}} - V_{\text{RCH}}$ $R_{\text{SENSE}} = 68 \text{ m}\Omega$	$V_{BUS} > V_{SLP},$	50		400	mA	
I _(TERM)	Termination Current Accuracy	[V _{CSIN} – V _{BAT}] from 3 mV to 20 mV		-25		+25	0/	
. ,	Termination Current Accuracy	$[V_{CSIN} - V_{BAT}]$ from 2	20 mV to 40 mV	-5		+5	%	
	Termination Current Deglitch Time	2 mV Overdrive			30		ms	
1.8 V Linear	Regulator							
V _{REG}	1.8 V Regulator Output	I _{REG} from 0 to 2 mA,	FAN5403-05	1.7	1.8	1.9	V	

Continued on the following page...

Electrical Specifications

Unless otherwise specified: according to the circuit of Figure 1; recommended operating temperature range for T_J and T_A ; V_{BUS} =5.0 V; HZ_MODE; OPA_MODE=0; (Charge Mode); SCL, SDA, OTG=0 or 1.8 V; and typical values are for T_J =25°C.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Input Power	Source Detection			1		<u> </u>
V _{IN(MIN)1}	VBUS Input Voltage Rising	To Initiate and Pass VBUS Validation		4.29	4.42	V
V _{IN(MIN)2}	Minimum VBUS during Charge	During Charging		3.71	3.94	V
t _{VBUS} VALID	VBUS Validation Time			30		ms
Special Cha	rger (V _{BUS}) (FAN5403 – FAN5405)		•	1	1	
V _{SP}	Special Charger Setpoint Accuracy		-3		+3	%
Input Currer	nt Limit			1	1	
		I _{IN} Set to 100 mA	88	93	98	
I _{INLIM}	Input Current Limit Threshold	I _{IN} Set to 500 mA	450	475	500	mA
V _{REF} Bias Ge	enerator		•		1	
	Bias Regulator Voltage	V _{BUS} > V _{IN(MIN)} or V _{BAT} > V _{BAT(MIN)}			6.5	V
V _{REF}	Short-Circuit Current Limit			20		mA
Battery Recl	harge Threshold			1		
	Recharge Threshold	Below V _(OREG)	100	120	150	mV
V _{RCH}	Deglitch Time	V _{BAT} Falling Below V _{RCH} Threshold		130		ms
STAT Outpu	t			1	2	
V _{STAT(OL)}	STAT Output Low	I _{STAT} =10 mA			0.4	V
ISTAT(OH)	STAT High Leakage Current	V _{STAT} =5 V			1	μA
Battery Dete						<u> </u>
IDETECT	Battery Detection Current before Charge Done (Sink Current) ⁽⁵⁾	Begins after Termination Detected		-0.80		mA
t DETECT	Battery Detection Time	and $V_{BAT} \leq V_{OREG} - V_{RCH}$		262		ms
Sleep Comp	arator		10			
V_{SLP}	Sleep-Mode Entry Threshold, V _{BUS} – V _{BAT}	2.3 V \leq V _{BAT} \leq V _{OREG} , V _{BUS} Falling	0	0.04	0.10	V
V_{SLP_EXIT}	Deglitch Time for VBUS Rising Above $V_{SLP} + V_{SLP_EXIT}$	Rising Voltage		30		ms
Power Swite	ches (see Figure 3)					
	Q3 On Resistance (VBUS to PMID)	I _{IN(LIMIT)} =500 mA		180	250	
R _{DS(ON)}	Q1 On Resistance (PMID to SW)			130	225	mΩ
	Q2 On Resistance (SW to GND)			150	225	
Charger PW	M Modulator		1	_		
f _{sw}	Oscillator Frequency		2.7	3.0	3.3	MHz
D _{MAX}	Maximum Duty Cycle				100	%
D _{MIN}	Minimum Duty Cycle			0		%
I _{SYNC}	Synchronous to Non-Synchronous Current Cut-Off Threshold ⁽⁶⁾	Low-Side MOSFET (Q2) Cycle-by- Cycle Current Limit		140		mA

Continued on the following page ...

7

Electrical Specifications

Unless otherwise specified: according to the circuit of Figure 1; recommended operating temperature range for T_J and T_A ; V_{BUS} =5.0 V; HZ_MODE; OPA_MODE=0; (Charge Mode); SCL, SDA, OTG=0 or 1.8 V; and typical values are for T_J =25°C.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Boost Mode	Operation (OPA_MODE=1, HZ_MODE	DE=0)		•	•	
M		2.5 V < V _{BAT} < 4.5 V, I _{LOAD} from 0 to 200 mA	4.80	5.07	5.17	v
V _{BOOST}	Boost Output Voltage at VBUS	2.7 V < V _{BAT} < 4.5 V, I _{LOAD} from 0 to 200 mA	4.85	5.07	5.17	
I _{BAT(BOOST)}	Boost Mode Quiescent Current	PFM Mode, V _{BAT} =3.6 V, I _{OUT} =0		140	300	μA
ILIMPK(BST)	Q2 Peak Current Limit		1100	1380	1660	mA
	Minimum Battery Voltage for Boost	While Boost Active		2.42		v
UVLO _{BST}	Operation	To Start Boost Regulator		2.58	2.70	v
VBUS Load	Resistance					
D		Normal Operation		1500		KΩ
R _{VBUS}	VBUS to PGND Resistance	Charger Validation		100		Ω
Protection a	nd Timers			•		
VELIC	VBUS Over-Voltage Shutdown	V _{BUS} Rising	6.09	6.29	6.49	V
VBUS _{OVP}	Hysteresis	V _{BUS} Falling		100		mV
I _{LIMPK(CHG)}	Q1 Cycle-by-Cycle Peak Current Limit	Charge Mode		2.3		А
V _{SHOBT}	Battery Short-Circuit Threshold	V _{BAT} Rising	1.95	2.00	2.05	v
VSHORT	Hysteresis	V _{BAT} Falling		100		v
I _{SHORT}	Linear Charging Current	VBAT < VSHORT	20	30	40	mA
т	Thermal Shutdown Threshold ⁽⁷⁾	T _J Rising		145		°C
T _{SHUTDWN}	Hysteresis ⁽⁷⁾	T _J Falling		10		U
T_{CF}	Thermal Regulation Threshold ⁽⁷⁾	Charge Current Reduction Begins		120		°C
t _{INT}	Detection Interval			2.1		s
tana	32-Second Timer ⁽⁸⁾	Charger Enabled	20.5	25.2	28.0	s
t _{32S}		Charger Disabled	18.0	25.2	34.0	5
t _{15MIN}	15-Minute Timer	15-Minute Mode (FAN5400, FAN5402, FAN5404, FAN5405)	12.0	13.5	15.0	min
Δt_{LF}	Low-Frequency Timer Accuracy	Charger Inactive	-25		25	%

Notes:

5. Negative current is current flowing from the battery to V_{BUS} (discharging the battery).

6. Q2 always turns on for 60 ns, then turns off if current is below I_{SYNC}.

7. Guaranteed by design; not tested in production.

8. This tolerance (%) applies to all timers on the IC, including soft-start and deglitching timers.

I²C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
		Standard Mode			100	
,		Fast Mode			400	1
f _{SCL}	SCL Clock Frequency	High-Speed Mode, $C_B \leq 100 \text{ pF}$			3400	kHz
		High-Speed Mode, $C_B \leq 400 \text{ pF}$			400 3400 1700 -	
	Bus-Free Time between STOP	Standard Mode		4.7		
t _{BUF}	and START Conditions	Fast Mode		1.3		μs
		Standard Mode		4		μS
t _{HD;STA}	START or Repeated START	Fast Mode		600		ns
	Hold Time	High-Speed Mode		160		ns
		Standard Mode		4.7		μS
		Fast Mode		4.7 1.3 4 600 160 4.7 1.3 160 320 4 600 120 4.7 600 120 4.7 600 120 14.7 100 120 3.45 900 70 150 0.1C _B 100	μs	
t _{LOW}	SCL LOW Period	High-Speed Mode, $C_B \leq 100 \text{ pF}$				ns
		High-Speed Mode, $C_B \le 400 \text{ pF}$		100 400 3400 1700 4.7 1.3 4 600 160 4.7 1.3 4 600 160 320 4 600 320 4 600 120 4.7 600 120 4.7 600 120 4.7 600 120 4.7 600 120 4.7 600 120 4.7 600 120 3.45 900 10 3.45 900 10 150 0.1C _B 100 10 80 20	ns	
_		Standard Mode		1		μS
		Fast Mode				ns
tніgн	SCL HIGH Period	High-Speed Mode, $C_B \le 100 \text{ pF}$			0 7 0 0 0 0	ns
	1	High-Speed Mode, $C_B \leq 400 \text{ pF}$				ns
-		Standard Mode				μS
t _{su;sta}	Repeated START Setup Time	Fast Mode)	ns
50,51A		High-Speed Mode				ns
		Standard Mode				
t _{su:dat}	Data Setup Time	Fast Mode				ns
50,DA1		High-Speed Mode				
		Standard Mode	0		3.45	μS
		Fast Mode	0			ns
t _{hd;dat}	Data Hold Time	High-Speed Mode, $C_B \le 100 \text{ pF}$	0			ns
		High-Speed Mode, $C_B \le 400 \text{ pF}$	0		-	ns
		Standard Mode		0.1Cp		110
		Fast Mode				-
t _{RCL}	SCL Rise Time	High-Speed Mode, $C_B \le 100 \text{ pF}$	20 +			ns
		High-Speed Mode, $C_B \leq 100 \text{ pF}$				
		Standard Mode	20 +			
		Fast Mode				
t _{FCL} S	SCL Fall Time	High-Speed Mode, $C_B \le 100 \text{ pF}$	20 +	1		ns
		High-Speed Mode, $C_B \le 400 \text{ pF}$				-
		Standard Mode	20 -			
too ·	SDA Rise Time	Fast Mode				-
t _{RDA} t _{RCL1}	Rise Time of SCL after a Repeated START Condition	High-Speed Mode, $C_B \le 100 \text{ pF}$	20 +	-		ns
INCL1	and after ACK Bit	• • • •				1
		High-Speed Mode, $C_B \le 400 \text{ pF}$	[20	100	

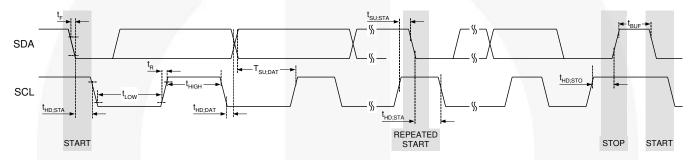
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I²C Timing Specifications

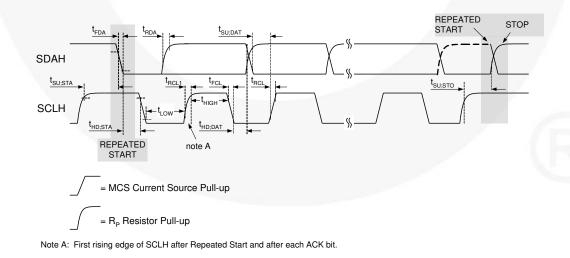
Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	
		Standard Mode	20 +	0.1C _B	300		
t _{fda} SE	SDA Fall Time	Fast Mode	20 +	0.1С _в	300		
	SDA Fail Time	High-Speed Mode, $C_B \leq 100 \text{ pF}$		10	80	ns	
		High-Speed Mode, $C_B \leq 400 \text{ pF}$		20	160		
		Standard Mode		4		μS	
tsu;sto	Stop Condition Setup Time	Fast Mode		600		ns	
		High-Speed Mode		160		ns	
CB	Capacitive Load for SDA, SCL				400	pF	

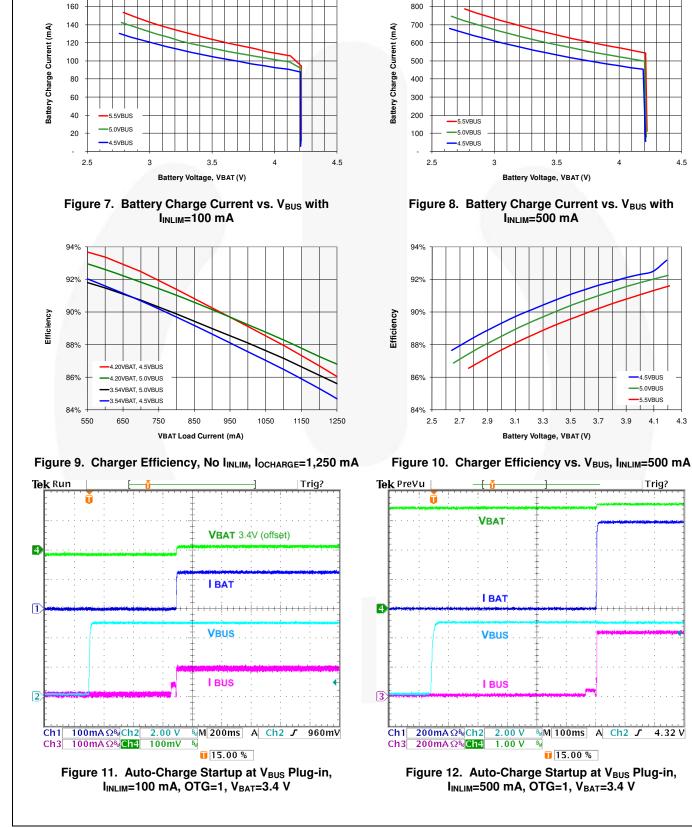
Timing Diagrams











4.5

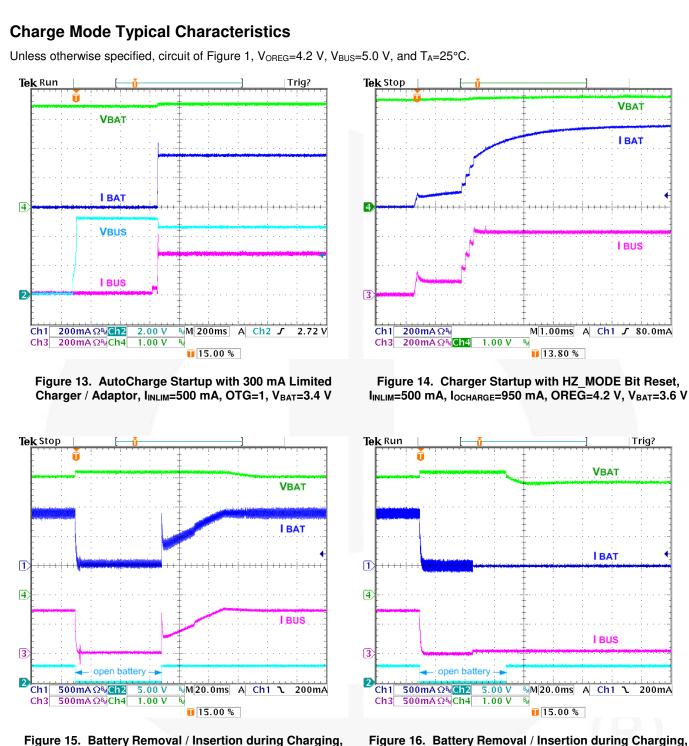
4.3

Charge Mode Typical Characteristics

180

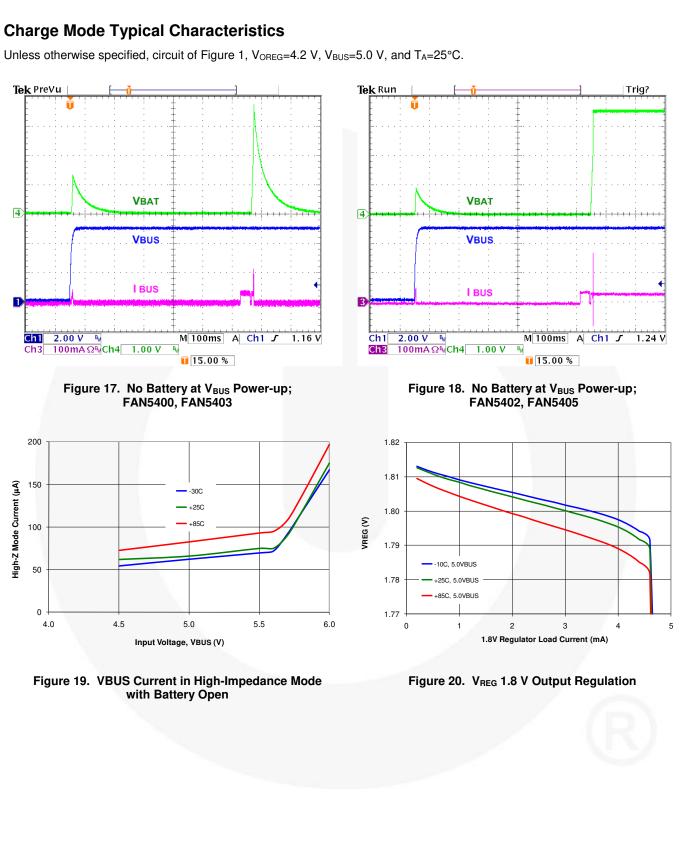
Unless otherwise specified, circuit of Figure 1, V_{OREG}=4.2 V, V_{BUS}=5.0 V, and T_A=25°C.

900



V_{BAT}=3.9 V, I_{OCHARGE}=950 mA, No I_{INLIM}, TE=0

VBAT=3.9 V, IOCHARGE=950 mA, NO IINLIM, TE=1



USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

FAN5400 Family —

FAN5400 Family — USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

-10C, 3.6VBAT

+25C, 3.6VBAT

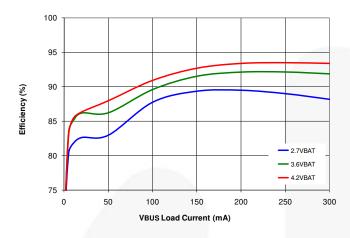
+85C, 3.6VBAT

250

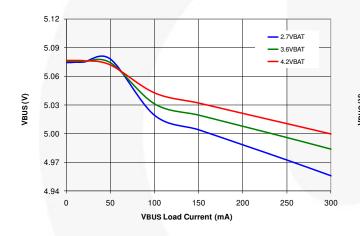
300

Boost Mode Typical Characteristics

Unless otherwise specified, using circuit of Figure 1, V_{BAT}=3.6 V, T_A=25°C.









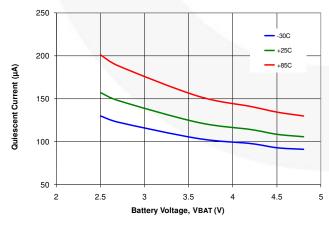


Figure 25. Quiescent Current

Figure 22. Efficiency Over-Temperature

VBUS Load Current (mA)

150

200

100

100

95

90

85

80

75

0

50

Efficiency (%)

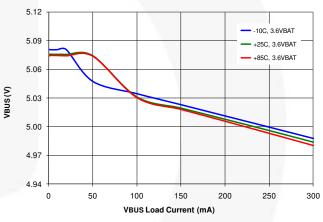
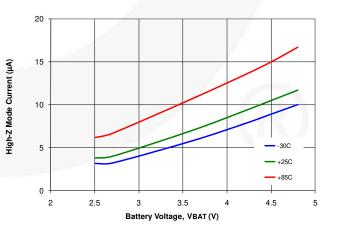
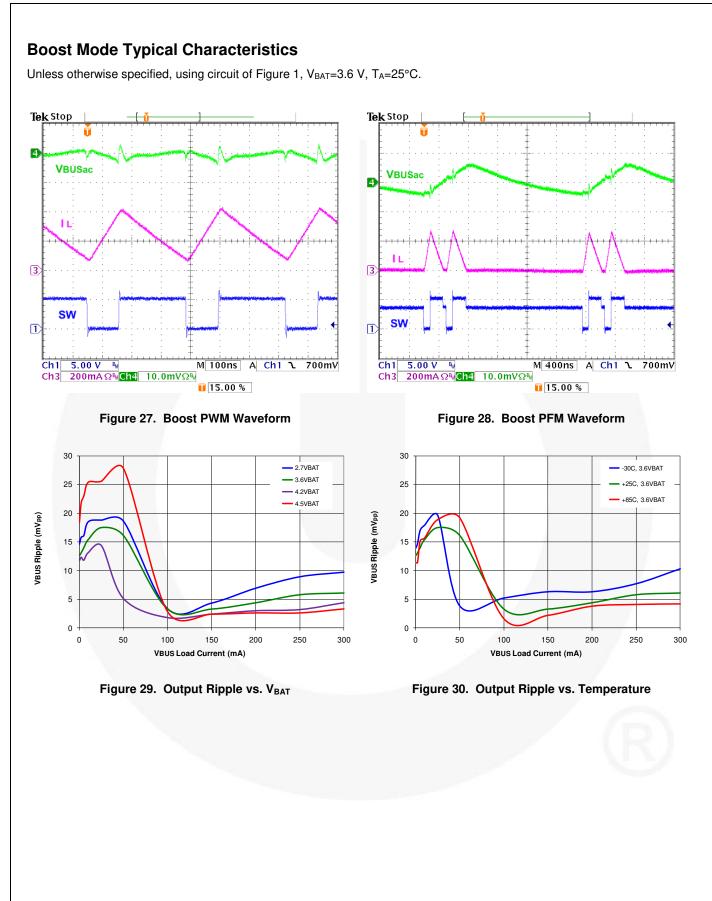


Figure 24. Output Regulation Over-Temperature



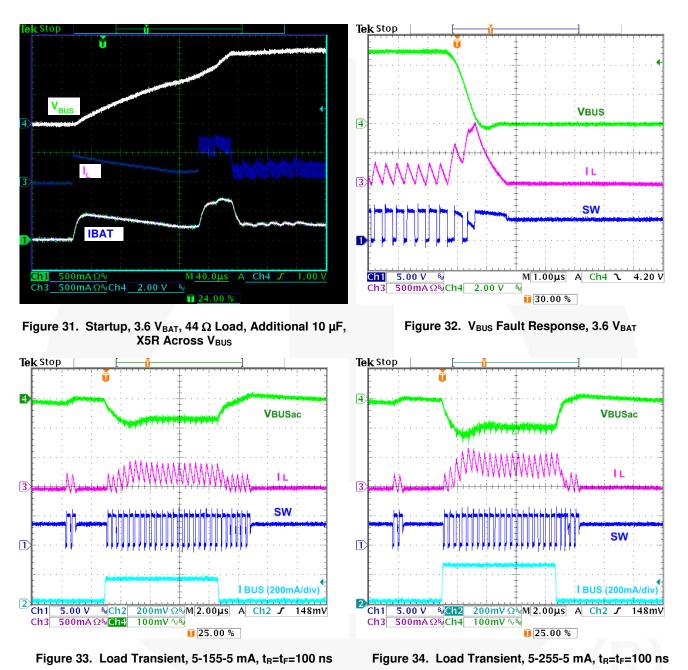






Boost Mode Typical Characteristics

Unless otherwise specified, using circuit of Figure 1, V_{BAT}=3.6 V, T_A=25°C.



Circuit Description / Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

FAN540X combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5 V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The FAN540X has three operating modes:

- 1. Charge Mode: Charges a single-cell Li-ion or Li-polymer battery.
- Boost Mode: Provides 5 V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.
- High-Impedance Mode: Both the boost and charging circuits are OFF in this mode. Current flow from VBUS to the battery or from the battery to VBUS is blocked in this mode. This mode consumes very little current from VBUS or the battery.

Note: Default settings are denoted by **bold typeface**.

Charge Mode

In Charge Mode, FAN540X employs four regulation loops:

- 1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface.
- 2. Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
- Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage rises, the battery's internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
- Temperature: If the IC's junction temperature reaches 120°C, charge current is continuously reduced until the IC's temperature stabilizes at 120°C.

In addition, the FAN5403-05 employ an additional loop to limit the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate "special chargers" that limit current to a lower current than might be available from a "normal" USB wall charger.

Battery Charging Curve

If the battery voltage is below V_{SHORT} , a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT} . The PWM charging circuit is then started and the battery is charged

with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The FAN540X is designed to work with a current-limited input source at VBUS. During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the amount of current available to charge the battery and power the system. The effect of I_{INLIM} on I_{CHARGE} can be seen in Figure 36.

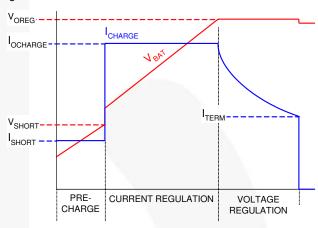


Figure 35. Charge Curve, ICHARGE Not Limited by IINLIM

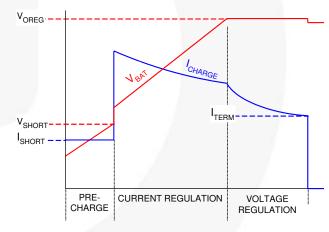


Figure 36. Charge Curve, I_{INLIM} Limits I_{CHARGE}

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit (REG1[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 3.5 V to 4.44 V in 20 mV increments, as shown in Table 3.

Table 3. OREG Bits (OREG[7:2]) vs. Charger V_{OUT} (V_{OREG}) Float Voltage

Decimal	Hex	VOREG	Decimal	Hex	VOREG
0	00	3.50	32	20	4.14
1	01	3.52	33	21	4.16
2	02	3.54	34	22	4.18
3	03	3.56	35	23	4.20
4	04	3.58	36	24	4.22
5	05	3.60	37	25	4.24
6	06	3.62	38	26	4.26
7	07	3.64	39	27	4.28
8	08	3.66	40	28	4.30
9	09	3.68	41	29	4.32
10	0A	3.70	42	2A	4.34
11	0B	3.72	43	2B	4.36
12	0C	3.74	44	2C	4.38
13	0D	3.76	45	2D	4.40
14	0E	3.78	46	2E	4.42
15	0F	3.80	47	2F	4.44
16	10	3.82	48	30	4.44
17	11	3.84	49	31	4.44
18	12	3.86	50	32	4.44
19	13	3.88	51	33	4.44
20	14	3.90	52	34	4.44
21	15	3.92	53	35	4.44
22	16	3.94	54	36	4.44
23	17	3.96	55	37	4.44
24	18	3.98	56	38	4.44
25	19	4.00	57	39	4.44
26	1A	4.02	58	ЗA	4.44
27	1B	4.04	59	3B	4.44
28	1C	4.06	60	3C	4.44
29	1D	4.08	61	3D	4.44
30	1E	4.10	62	3E	4.44

The following charging parameters can be programmed by the host through $\ensuremath{\mathsf{I}}^2\ensuremath{\mathsf{C}}$:

Table 4.	Programmable	Charging	Parameters
----------	--------------	----------	------------

Parameter	Name	Register				
Output Voltage Regulation	VOREG	REG2[7:2]				
Battery Charging Current Limit	I _{OCHRG}	REG4[6:4]				
Input Current Limit	I _{INLIM}	REG1[7:6]				
Charge Termination Limit	I _{TERM}	REG4[2:0]				
Weak Battery Voltage	V_{LOWV}	REG1[5:4]				

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V_{OREG} V_{RCH}
- VBUS Power On Reset (POR) clears and the battery voltage is below the weak battery threshold (V_{LOWV}).
 This occurs for all versions except the FAN5401.
- CE or HZ_MODE is reset through I²C write to CONTROL1 (R1) register.

Charge Current Limit (IOCHARGE)

Table 5. I_{OCHARGE} (REG4 [6:4]) Current as Function of I_{OCHARGE} Bits and R_{SENSE} Resistor Values

DEC	DEC BIN HEX VRSENSE		I _{OCHARGE} (mA)		
DEC	DIN	HEX	(mV)	68 mΩ	100 mΩ
0	000	00	37.4	550	374
1	001	01	44.2	650	442
2	010	02	51.0	750	510
3	011	03	57.8	850	578
4	100	04	64.6	950	646
5	101	05	71.4	1050	714
6	110	06	78.2	1150	782
7	111	07	85.0	1250	850

Termination Current Limit

Current charge termination is enabled when TE (REG1[3])=1. Typical termination current values are given in Table 6.

Table 6. I_{TERM} Current as Function of I_{TERM} Bits (REG4[2:0]) and R_{SENSE} Resistor Values

	FAN5400 - FAN5402			400 - FAN5402 FAN5403 - FAN		
	V _{RSENSE}	I _{TERM} (mA)		VRSENSE	I _{TERM} (mA)	
ITERM	(mV)	68 mΩ	100 mΩ	(mV)	68 mΩ	100 mΩ
0	3.4	50	34	3.3	49	33
1	6.8	100	68	6.6	97	66
2	10.2	150	102	9.9	146	99
3	13.6	200	136	13.2	194	132
4	17.0	250	170	16.5	243	165
5	20.4	300	204	19.8	291	198
6	23.8	350	238	23.1	340	231
7	27.2	400	272	26.4	388	264

When the charge current falls below I_{TERM} for a period of 32 ms; PWM charging stops and the STAT bits change to READY (00) for about 500 ms while the IC determines whether the battery and charging source are still connected. The STAT bits then change to CHARGE DONE (10), provided the battery and charger are still connected.

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulate the output voltage and battery charge currents. The synchronous rectifier (Q2) has a negative current limit that turns off Q2 at 140 mA to prevent current flow from the battery.

Safety Timer

This section references Figure 41 and Figure 42.

At the beginning of charging, the IC starts a 15-minute timer (t_{15MIN}). When this timer times out, charging is terminated. Writing to any register through I²C stops and resets the t_{15MIN} timer, which in turn starts a 32-second timer (t_{32S}). Setting the TMR_RST bit (REG0[7]) resets the t_{32S} timer. If the t_{32S} timer times out, charging is terminated, the registers are set to their default values, and charging resumes using the default values with the t_{15MIN} timer running.

Normal charging is controlled by the host with the t_{32S} timer running to ensure that the host is alive. Charging with the t_{15MIN} timer running is used for charging that is unattended by the host. If the t_{15MIN} timer expires, the IC turns off the charger, sets the \overline{CE} bit, and indicates a timer fault (110) on the FAULT bits (REG0[2:0]). This sequence prevents overcharge if the host fails to reset the t_{32S} timer.

V_{BUS} POR / Non-Compliant Charger Rejection

When the IC detects that V_{BUS} has risen above V_{IN(MIN)1} (4.4 V), the IC applies a 110 Ω load from VBUS to GND. To clear the VBUS POR (Power-On-Reset) and begin charging, VBUS must remain above V_{IN(MIN)1} and below VBUS_{OVP} for t_{VBUS_VALID} (30 ms) before the IC initiates charging. The VBUS validation sequence always occurs before charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation).

tvBUS_VALID ensures that unfiltered 50 / 60 Hz chargers and other non-compliant chargers are rejected.

USB-Friendly Boot Sequence

For all versions except FAN5401, FAN5404

At VBUS POR, when the battery voltage is above the weak battery threshold (V_{LOWV}), the IC operates in accordance with its I^2C register settings. If $V_{BAT} < V_{LOWV}$, the IC sets all registers to their default values and enables the charger using an input current limit controlled by the OTG pin (100 mA if OTG is LOW and 500 mA if OTG is HIGH). This feature can revive a battery whose voltage is too low to ensure reliable host operation. Charging continues in the absence of host communication even after the battery has reached VOREG, whose default value is 3.54 V, and the charger remains active until t_{15MIN} times out. Once the host processor begins writing to the IC, charging parameters are set by the host, which must continually reset the tags timer to continue charging using the programmed charging parameters. If t325 times out, the register defaults are loaded, the FAULT bits are set to 110, STAT is pulsed HIGH, and charging continues with default charge parameters.

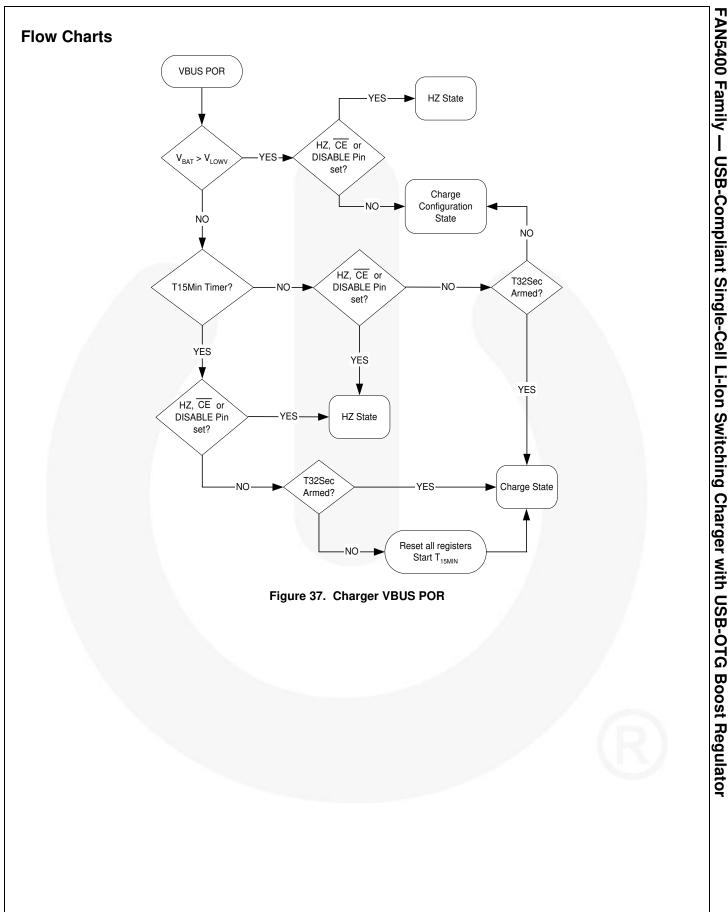
The FAN5401 and FAN5404 do not automatically initiate charging at VBUS POR. Instead, they wait for the host to initiate charging through I^2C commands.

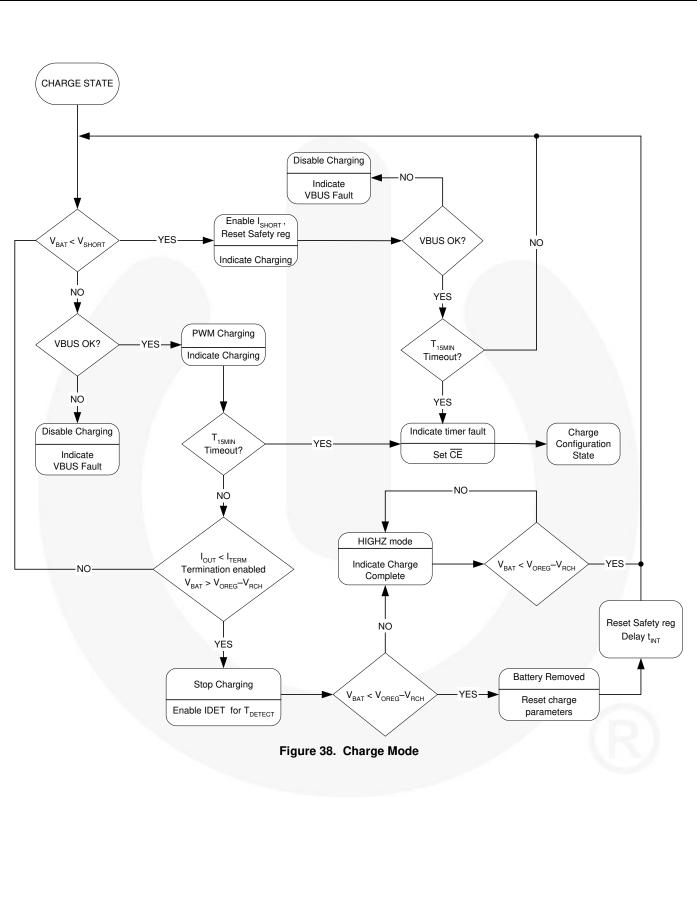
Input Current Limiting

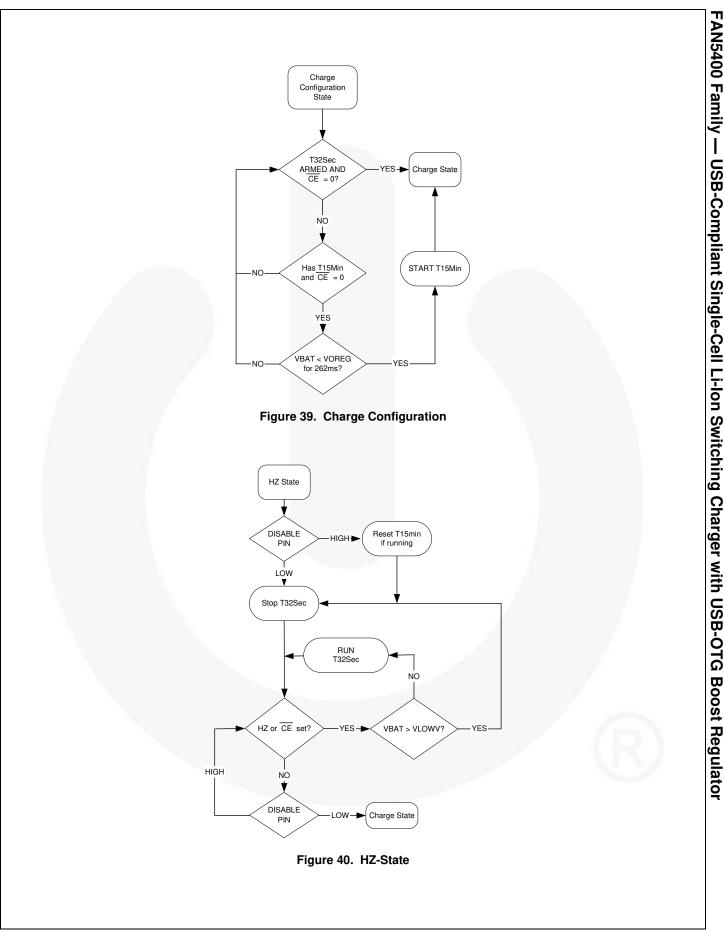
To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

I _{INLIM} REG1[7:6]	Input Current Limit
00	100 mA
01	500 mA
10	800 mA
11	No limit

For all versions except the FAN5401 and FAN5404, the OTG pin establishes the input current limit when t_{15MIN} is running. For the FAN5401 and FAN5404, no charging occurs automatically at VBUS POR, so the input current limit is established by the I_{INLIM} bits.







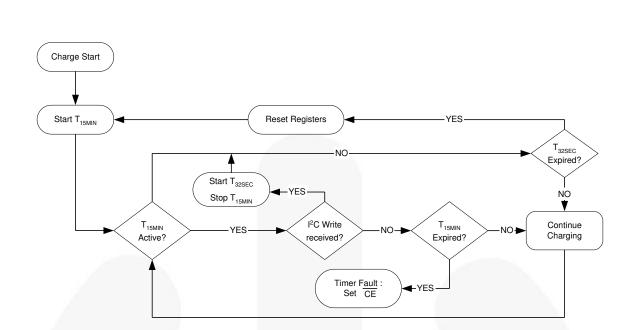


Figure 41. Timer Flow Chart for FAN5400, FAN5402, FAN5403, FAN5405

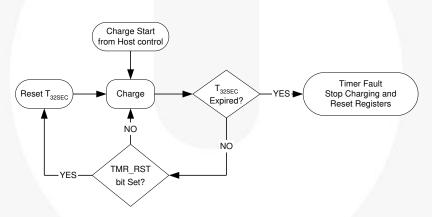


Figure 42. Timer Flow Chart for FAN5401, FAN5404

Special Charger

FAN5403-05 Only

The FAN5403, FAN5404, and FAN5405 have additional functionality to limit input current in case a current-limited "special charger" is supplying VBUS. The FAN5403-05 slowly increases the charging current until either:

IINLIM or IOCHARGE is reached

or

V_{BUS}=V_{SP}.

If V_{BUS} collapses to V_{SP} when the current is ramping up, the FAN5403-05 charge with an input current that keeps V_{BUS}=V_{SP}. When the V_{SP} control loop is limiting the charge current, the SP bit (REG5[4]) is set.

Table 8. V_{SP} as Function of SP Bits (REG5[2:0])

S			
DEC	BIN	HEX	V _{SP}
0	000	00	4.213
1	001	01	4.293
2	010	02	4.373
3	011	03	4.453
4	100	04	4.533
5	101	05	4.613
6	110	06	4.693
7	111	07	4.773

Safety Settings

FAN5403-FAN5405 Only

The FAN5403-05 contain a SAFETY register (REG6) that prevents the values in OREG (REG2[7:2]) and IOCHARGE (REG4[6:4]) from exceeding the values of the VSAFE and ISAFE values.

After V_{BAT} exceeds V_{SHORT} , the SAFETY register is loaded with its default value and may be written only before any other register is written. After writing to any other register, the SAFETY register is locked until V_{BAT} falls below V_{SHORT} .

The ISAFE (REG6[6:4]) and VSAFE (REG6[3:0]) registers establish values that limit the maximum values of $I_{OCHARGE}$ and V_{OREG} used by the control logic. If the host attempts to write a value higher than VSAFE or ISAFE to OREG or IOCHARGE, respectively; the VSAFE, ISAFE value appears as the OREG, IOCHARGE register value, respectively.

Table 9. I_{SAFE} (I_{OCHARGE} Limit) as Function of ISAFE Bits (REG6[6:4])

ISAFE	E (REG6	6[6:4])	

DEC	BIN	HEX	\/ (m\/)	I _{SAFE}	(mA)
DEC	DIN	ПЕЛ	V _{RSENSE} (mV)	68 mΩ	100 m Ω
0	000	00	37.4	550	374
1	001	01	44.2	650	442
2	010	02	51.0	750	510
3	011	03	57.8	850	578
4	100	04	64.6	950	646
5	101	05	71.4	1050	714
6	110	06	78.2	1150	782
7	111	07	85.0	1250	850

Table 10. V_{SAFE} (V_{OREG} Limit) as Function of VSAFE Bits (REG6[3:0])

VSAFE (REG6[3:0])				
DEC	BIN	HEX	Max. OREG (REG2[7:2])	VOREG Max.
0	0000	00	100011	4.20
1	0001	01	100100	4.22
2	0010	02	100101	4.24
3	0011	03	100110	4.26
4	0100	04	100111	4.28
5	0101	05	101000	4.30
6	0110	06	101001	4.32
7	0111	07	101010	4.34
8	1000	08	101011	4.36
9	1001	09	101100	4.38
10	1010	0A	101101	4.40
11	1011	0B	101110	4.42
12	1100	0C	101111	4.44
13	1101	0D	110000	4.44
14	1110	0E	110001	4.44
15	1111	0F	110010	4.44

Thermal Regulation and Protection

When the IC's junction temperature reaches T_{CF} (about 120°C), the charger reduces its output current to 550 mA to prevent overheating. If the temperature increases beyond $T_{SHUTDOWN}$; charging is suspended, the FAULT bits are set to 101, and STAT is pulsed HIGH. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes at programmed current after the die cools to about 120°C.